



Material Content Data Sheet



Sales Product Name				IPB160N04S4-H1		Issued		23. January 2018	
MA#				MA001049460					
Package				PG-TO263-7-3		Weight*		1535.98 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.138	0.33	0.33	3345	3345	
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		523		
	inorganic material	phosphorus	7723-14-0	0.241	0.02		157		
	non noble metal	copper	7440-50-8	801.714	52.19	52.26	521955	522636	
wire	non noble metal	aluminium	7429-90-5	116.741	7.60	7.60	76004	76004	
encapsulation	organic material	carbon black	1333-86-4	7.327	0.48		4771		
	plastics	epoxy resin	-	80.601	5.25		52476		
	inorganic material	silicondioxide	60676-86-0	400.563	26.08	31.81	260787	318034	
leadfinish	non noble metal	tin	7440-31-5	12.317	0.80	0.80	8019	8019	
plating	non noble metal	nickel	7440-02-0	0.269	0.02		175		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	175	
solder	noble metal	silver	7440-22-4	0.098	0.01		64		
	non noble metal	tin	7440-31-5	0.078	0.01		51		
	non noble metal	lead	7439-92-1	3.739	0.24	0.26	2434	2549	
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69		
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	copper	7440-50-8	106.210	6.91	6.92	69148	69238	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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